

FORM PTO-1083

In re Application of: Shinji TAKEDA et al.

Serial No. 09/785,433

Filed: February 20, 2001

For: SEMICONDUCTOR DEVICE AND PROCESS FOR FABRICATION THEREOF

ASSISTANT COMMISSIONER FOR PATENTS

Box: Fee Amendment

Washington, D. C. 20231

Sir:

Transmitted herewith is an Amendment in the above-identified application.

- [] Small entity status of this application under 37 CFR 1.9 and 1.27 has been established by a verified statement previously submitted.
- [] A verified statement to establish small entity status under 37 CFR 1.9 and 1.27 is hereby claimed.
- [XXX] No additional fee is required.

The fee has been calculated as shown below:

(COL. 1)			(COL. 2)			(COL. 3)			SMALL ENTITY		OTHER THAN A SMALL ENTITY	
CLAIMS REMAINING AFTER AMENDMENT			HIGHEST NO. PREVIOUSLY PAID FOR			PRESENT EXTRA			ADDIT. OR RATE FEE		RATE FEE	
TOTAL	*	17	MINUS	**	53	=	0		X 9 = \$		X 18 = \$	0
INDEP.	*	5	MINUS	***	17	=	0		X 42 = \$		X 84 = \$	0
[] FIRST PRESENTATION OF MULTIPLE DEP. CLAIM									X140 = \$		X280 = \$	
TOTAL												
ADDIT. FEE \$ _____ OR TOTAL \$ -0-												

- * If the entry in Col. 1 is less than the entry in Col. 2, write "0" in Col. 3.
- ** If the "Highest No. Previously Paid For" IN THIS SPACE is less than 20, write "20" in this space.
- *** If the "Highest No. Previously Paid For" IN THIS SPACE is less than 3, write "3" in this space.
- The "Highest No. Previously Paid For" (Total or Independent) is the highest number found from the equivalent box in Col. 1 of a prior Amendment or the number of claims originally filed.

- [] Please charge my Deposit Account No. 501281 in the amount of \$ _____. A duplicate copy of this sheet is attached.
- [] A check (No. _____) in the amount of \$ _____ is attached.
- [XXX] The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 501281. A duplicate copy of this sheet is attached.

- [XX] Any filing fees under 37 CFR 1.16 for the presentation of extra claims.
- [XX] Any patent application processing fees under 37 CFR 1.17.

Joerg-Uwe Szipl
Reg. No. 31,799

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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4-1-02

In re application of)
Shinji TAKEDA et al.) Atty. Docket No.: TM&K0007
Serial No. 09/785,436) Group Art Unit: 2813
Filed: February 20, 2001) Examiner: Scott Geyer
For: SEMICONDUCTOR DEVICE AND)
PROCESS FOR FABRICATION) Date: March 25, 2002
THEREOF)

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AMENDMENT (C)

BOX: Fee Amendment
Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the official Office Action dated September 25, 2001, please amend the above-captioned application as follows:

IN THE CLAIMS

- ✓ Please cancel claims 25-28, 30, 32-35 and 39-48 without prejudice.
- ✓ Kindly add new claims 49-60 as follows:

49. (NEW) A process for fabricating a semiconductor device according to claim 38,
C¹ wherein said process is performed with said filmy die-bonding material comprising polyimide
and epoxy resin comprising one or more resins selected from the group consisting of silicone
resin, acrylic resin, polyimide resin and epoxy resin; and
said filmy die-bonding material has a water absorption of 1.5% by volume or less.